

2.5V Drive Nch MOSFET

1.5V Drive Pch MOSFET

TT8M2

●Structure

Silicon N-channel MOSFET/
Silicon P-channel MOSFET

●Features

- 1) Low on-state resistance.
- 2) Low voltage drive.
- 3) High power package.

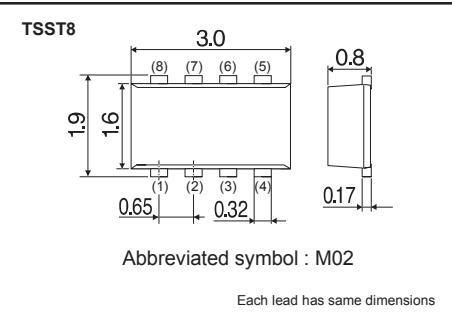
●Application

Switching

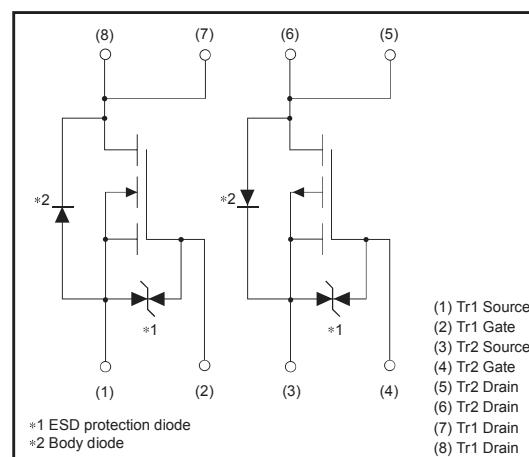
●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
TT8M2	○	

●Dimensions (Unit : mm)



●Inner circuit



●Absolute maximum ratings (Ta=25°C)

<Tr1 : Nch>

Parameter	Symbol	Limits	Unit
Drain-source voltage	V _{DSS}	30	V
Gate-source voltage	V _{GSS}	±12	V
Drain current	Continuous	I _D	A
	Pulsed	I _{DP} *1	A
Source current (Body diode)	Continuous	I _S	A
	Pulsed	I _{SP} *1	A

*1 P_W≤10μs, Duty cycle≤1%

<Tr2 : Pch>

Parameter		Symbol	Limits	Unit
Drain-source voltage		V _{DSS}	-20	V
Gate-source voltage		V _{GSS}	±10	V
Drain current	Continuous	I _D	±2.5	A
	Pulsed	I _{DP} *1	±10	A
Source current (Body diode)	Continuous	I _S	-0.8	A
	Pulsed	I _{SP} *1	-10	A

*1 Pw≤10μs, Duty cycle≤1%

<Tr1 AND Tr2>

Parameter	Symbol	Limits	Unit
Total power dissipation	P _D *2	1.25	W / TOTAL
		1.0	W / ELEMENT
Channel temperature	T _{ch}	150	°C
Range of Storage temperature	T _{stg}	-55 to +150	°C

*2 Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

< Characteristics for the Tr1(Nch).>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	—	—	±10	μA	V _{GS} =±12V, V _{DS} =0V
Drain-source breakdown voltage	V _{(BR) DSS}	30	—	—	V	I _D =1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	—	—	1	μA	V _{DS} =30V, V _{GS} =0V
Gate threshold voltage	V _{GS(th)}	0.5	—	1.5	V	V _{DS} =10V, I _D =1mA
Static drain-source on-state resistance	R _{DS(on)*}	—	65	90	mΩ	I _D =2.5A, V _{GS} =4.5V
		—	70	95	mΩ	I _D =2.5A, V _{GS} =4V
		—	95	130	mΩ	I _D =2.5A, V _{GS} =2.5V
Forward transfer admittance	Y _{fs} *	2.2	—	—	S	V _{DS} =10V, I _D =2.5A
Input capacitance	C _{iss}	—	180	—	pF	V _{DS} =10V
Output capacitance	C _{oss}	—	60	—	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	—	35	—	pF	f=1MHz
Turn-on delay time	t _{d(on)} *	—	7	—	ns	V _{DD} =15V I _D =1.2A
Rise time	t _r *	—	30	—	ns	V _{GS} =4.5V
Turn-off delay time	t _{d(off)} *	—	20	—	ns	R _L =12.5Ω
Fall time	t _f *	—	20	—	ns	R _G =10Ω
Total gate charge	Q _g *	—	3.2	—	nC	V _{DD} =15V, I _D =2.5A
Gate-source charge	Q _{gs} *	—	0.9	—	nC	V _{GS} =4.5V
Gate-drain charge	Q _{gd} *	—	0.4	—	nC	R _L =6Ω, R _G =10Ω

*Pulsed

●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _{SD} *	—	—	1.2	V	I _S =2.5A, V _{GS} =0V

*Pulsed

●Electrical characteristics (Ta=25°C)

< Characteristics for the Tr2(Pch).>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I _{GSS}	—	—	±10	µA	V _{GS} =±10V, V _{DS} =0V
Drain-source breakdown voltage	V _{(BR) DSS}	-20	—	—	V	I _D = -1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	—	—	-1	µA	V _{DS} = -20V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	-0.3	—	-1.0	V	V _{DS} = -10V, I _D = -1mA
Static drain-source on-state resistance	R _{DS (on)*}	—	49	68	mΩ	I _D = -2.5A, V _{GS} = -4.5V
		—	68	95	mΩ	I _D = -1.2A, V _{GS} = -2.5V
		—	100	150	mΩ	I _D = -1.2A, V _{GS} = -1.8V
		—	140	280	mΩ	I _D = -0.5A, V _{GS} = -1.5V
Forward transfer admittance	Y _{fs} *	2.5	—	—	S	V _{DS} = -10V, I _D = -2.5A
Input capacitance	C _{iss}	—	1270	—	pF	V _{DS} = -10V
Output capacitance	C _{oss}	—	100	—	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	—	90	—	pF	f=1MHz
Turn-on delay time	t _{d (on)} *	—	9	—	ns	V _{DD} = -10V
Rise time	t _r *	—	30	—	ns	I _D = -1.2A
Turn-off delay time	t _{d (off)} *	—	120	—	ns	V _{GS} = -4.5V
Fall time	t _f *	—	85	—	ns	R _L = 8.3Ω
Total gate charge	Q _g *	—	12	—	nC	R _G =10Ω
Gate-source charge	Q _{gs} *	—	2.5	—	nC	V _{GS} = -4.5V
Gate-drain charge	Q _{gd} *	—	2.0	—	nC	R _L =4Ω, R _G =10Ω

*Pulsed

●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V _{SD} *	—	—	-1.2	V	I _S = -2.5A, V _{GS} =0V

*Pulsed

●Electrical characteristics curves
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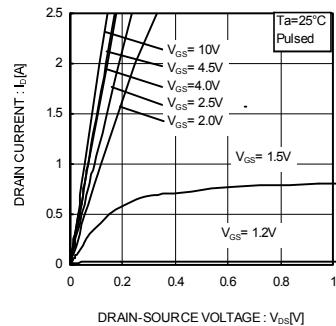


Fig.1 Typical Output Characteristics (I)

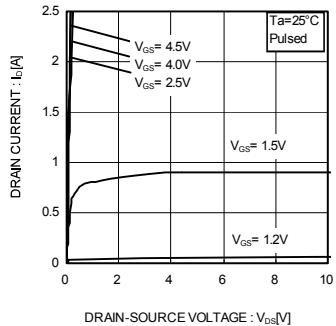


Fig.2 Typical Output Characteristics (II)

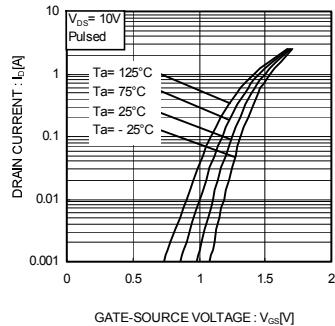


Fig.3 Typical Transfer Characteristics

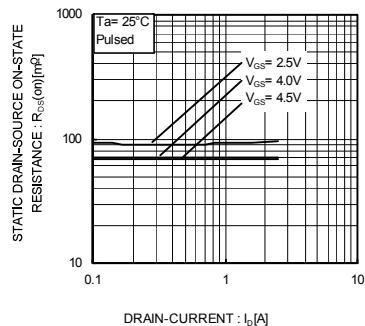


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current (I)

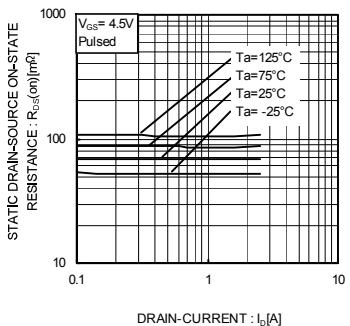


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current (II)

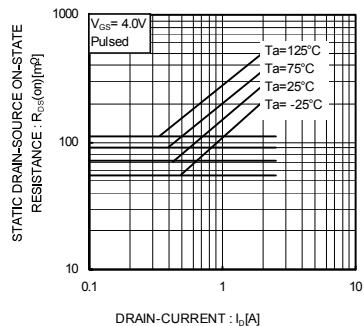


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current (III)

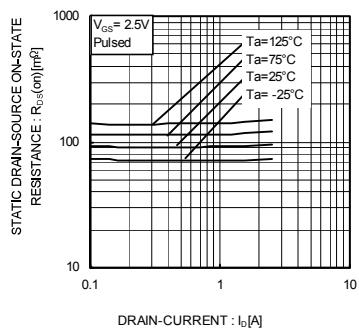


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (IV)

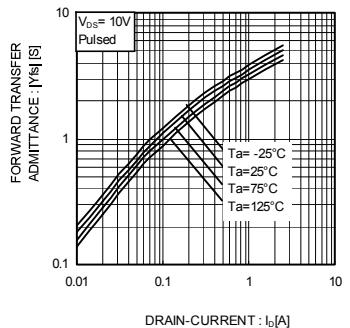


Fig.8 Forward Transfer Admittance vs. Drain Current

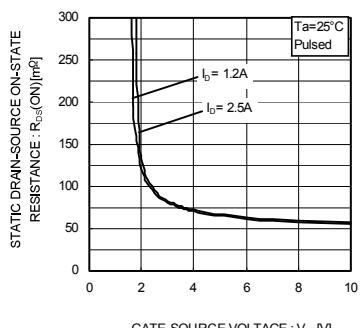


Fig.9 Static Drain-Source On-State Resistance vs. Gate Source Voltage

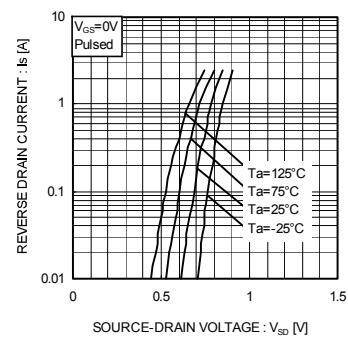


Fig.10 Reverse Drain Current
vs. Source-Drain Voltage

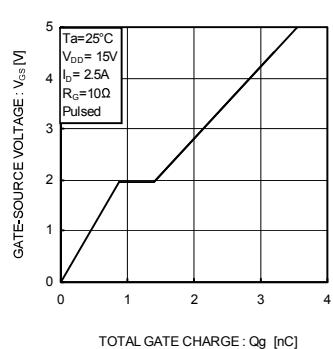


Fig.11 Dynamic Input Characteristics

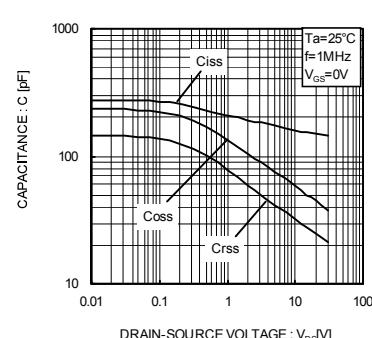


Fig.12 Typical Capacitance
vs. Drain-Source Voltage

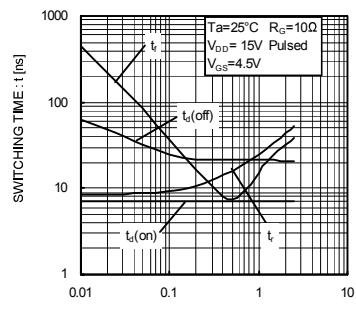


Fig.13 Switching Characteristics

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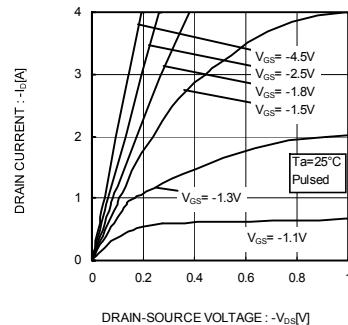


Fig.1 Typical Output Characteristics (I)

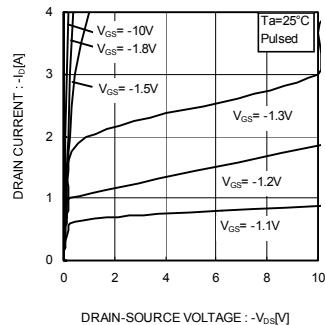


Fig.2 Typical Output Characteristics (II)

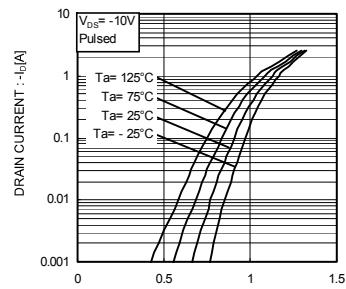


Fig.3 Typical Transfer Characteristics

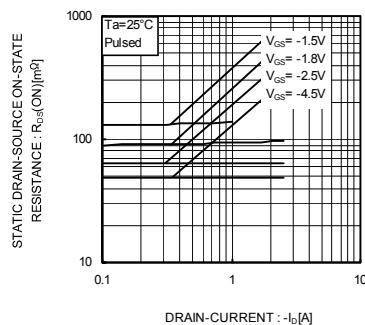


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

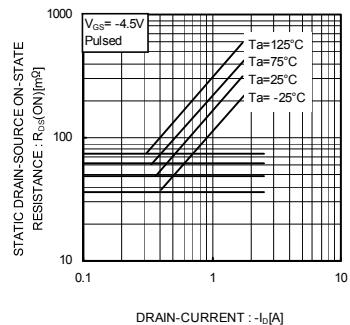


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

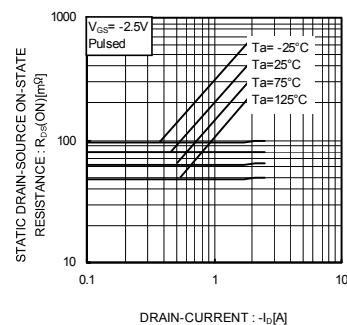


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(III)

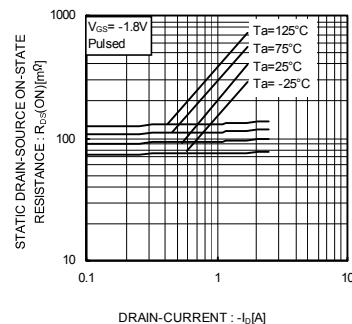


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

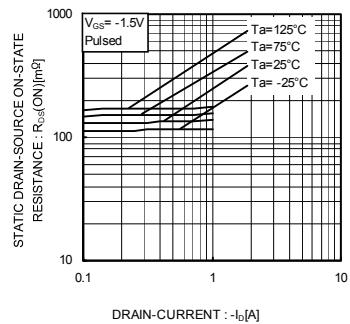


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(V)

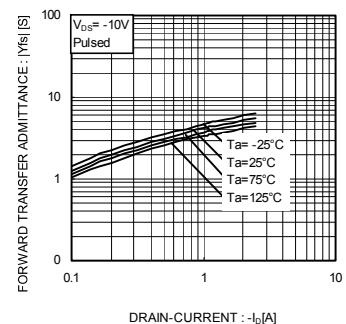


Fig.9 Forward Transfer Admittance vs. Drain Current

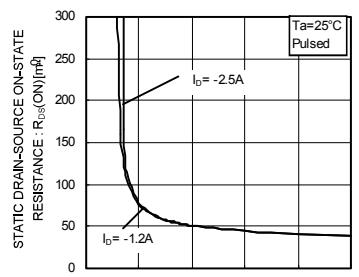
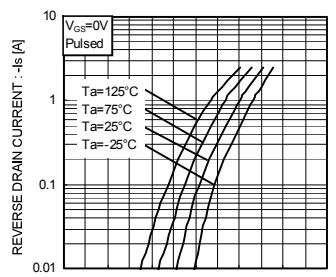
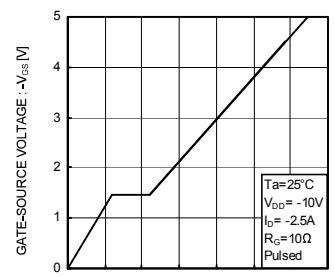
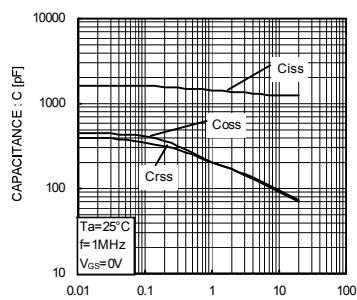
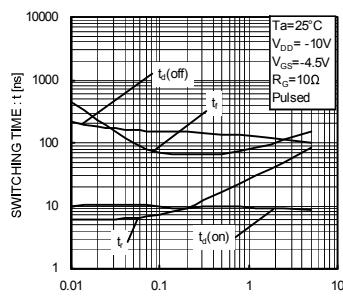
GATE-SOURCE VOLTAGE : $-V_{GS}$ [V]Fig.10 Static Drain-Source On-State
Resistance vs. Gate Source VoltageSOURCE-DRAIN VOLTAGE : $-V_{SD}$ [V]Fig.11 Reverse Drain Current
vs. Source-Drain VoltageTOTAL GATE CHARGE : Q_g [nC]

Fig.12 Dynamic Input Characteristics

DRAIN-SOURCE VOLTAGE : $-V_{DS}$ [V]
Fig.13 Typical Capacitance
vs. Drain-Source VoltageSWITCHING TIME : t [ns]
Fig.14 Switching Characteristics

●Measurement circuits

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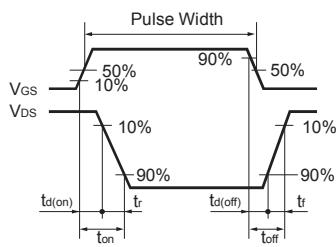
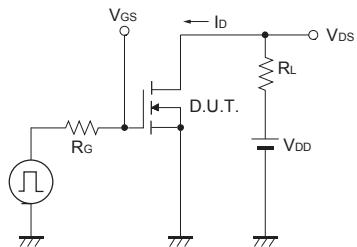


Fig.1-1 Switching Time Measurement Circuit

Fig.1-2 Switching Waveforms

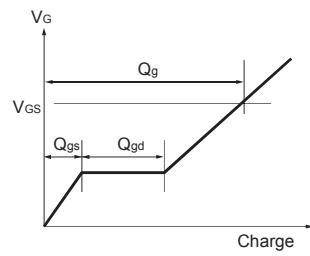
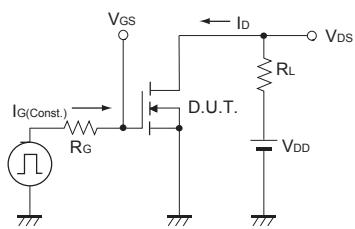


Fig.2-1 Gate charge measurement circuit

Fig.2-2 Gate Charge Waveform

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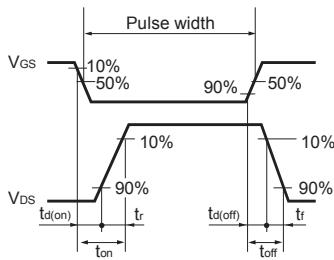
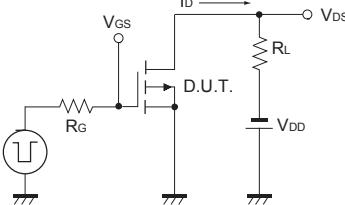


Fig.3-1 Switching time measurement circuit

Fig.3-2 Switching waveforms

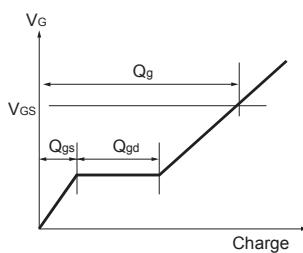
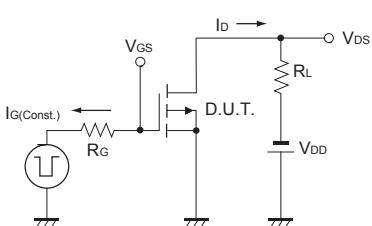


Fig.4-1 Gate charge measurement circuit

Fig.4-2 Gate charge waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment.
Please consider to design ESD protection circuit.

Notes

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